

Amendments to the Specification:

Please amend paragraph [35] as follows:

ai [35] When a shorting defect is repaired as described in the first embodiment above, the size of the area on the TFT panel to which the molten scan line metal 10 scatters when laser 9 removes the scan line is before and after ~~above and below~~ the shorted intersection depends on the characteristics of the laser, but is typically 100  $\mu\text{m}$  to 200  $\mu\text{m}$  in diameter. As shown in Fig. 1, this 100  $\mu\text{m}$  to 200  $\mu\text{m}$  diameter area is coated with an insulation film material 13 using a glass pipette 12, and the insulation film material 13 is heat cured, for example, to form an insulation film over the repair site. The thickness of this locally formed insulation film is 0.3  $\mu\text{m}$  to 1  $\mu\text{m}$ , producing a thicker film portion relative to the unrepaired surrounding at the repair site.